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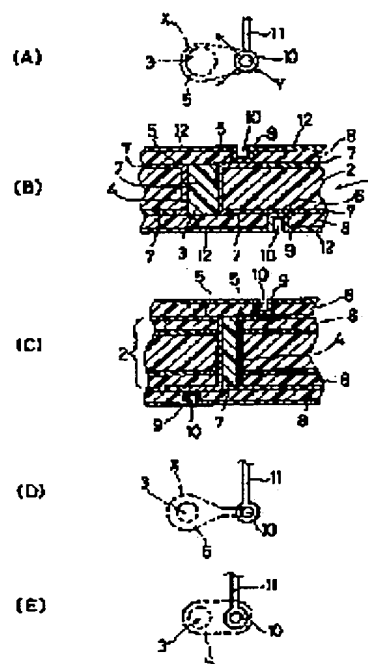
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**(54) MULTILAYER PRINTED WIRING BOARD**

(57)Abstract:

**PROBLEM TO BE SOLVED:** To stably connect vias to pads if the pads deviate from a mask film by forming tear-drop-like lands of through-holes to be electrically connected to the vias of a multilayer wiring board.

**SOLUTION:** The multilayer printed wiring board 1 has a core board 2 having through-holes 3 and a layer insulating layer 8 formed on the upper surface of the board 2. This layer 8 has through-hole lands 5 having recesses where vias 10 are formed below which a conductor layer 9 is formed and circuit pattern 11 connected to this layer 9 is also formed. The through-holes 5 have tear-drop shapes and vias 10 are connected in the through-hole lands 5 which are hence integrated with pads connected to the vias 10. Thus, the connection area is expanded to stabilize the connection.

**LEGAL STATUS**

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